AMENDMENTS TO THE CLAIMS:

Claims 1-14 **(Canceled)**

15. **(Currently Amended)** A method for detachably attaching a device to a substructure, said method comprising the steps of:

a) attaching a pair of rails to opposed sides of the device;

b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;

c) aligning ~~repositioning~~ an alignment pin extending from one of the rails with a hole in one of the guides to align an electrical connector of the device with an electrical connector mounted on the substructure;

d) securing a cross member interconnecting the pair of rails with a face plate attached to the substructure to secure the device with the substructure; and

e) dissipating any attendant electrostatic charge upon execution of said step of sliding.

16. **(Original)** The method as set forth in Claim 15 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

17. **(Currently Amended)** The method as set forth in Claim 15 [[16]] including the step of contacting a plate ~~secured in the guide and~~ extending from the substructure with a [[the]]

spring during execution of said step of translating.

Claims 18-20 **(Canceled)**

21. **(New)** The method as set forth in Claim 16 including the step of contacting a plate extending from the superstructure with the spring during extension of said step of translating.

22. **(New)** A method for detachably attaching a device to a substructure, said method comprising the steps of:

a) attaching a pair of rails to opposed sides of the device;

b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;

c) aligning an alignment pin extending from one of the rails with a hole in one of the guides to align an electrical connector of the device with an electrical connector mounted on the substructure; and

d) dissipating any attendant electrostatic charge upon execution of said step of engaging.

23. **(New)** The method as set forth in Claim 22 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

24. **(New)** The method as set forth in Claim 22 including the step of contacting a plate

extending from the substructure with a spring during execution of said step of translating.

25. **(New)** The method as set forth in Claim 22 including the step of contacting a plate extending from the superstructure with the spring during extension of said step of translating.

26. **(New)** A method for detachably attaching a device to a substructure, said method comprising the steps of:

a) attaching a pair of rails to opposed sides of the device;

b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;

c) securing a cross member interconnecting the pair of rails with a face plate attached to the substructure to secure the device with the substructure; and

d) dissipating any attendant electrostatic charge upon execution of said step of engaging.

27. **(New)** The method as set forth in Claim 26 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

28. **(New)** The method as set forth in Claim 26 including the step of contacting a plate extending from the substructure with a spring during execution of said step of translating.

29. **(New)** The method as set forth in Claim 27 including the step of contacting a plate

extending from the superstructure with the spring during extension of said step of translating.